PRODUCT PREVIEW

Contact:

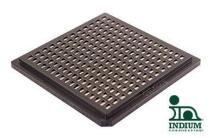
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Indium Corporation to Feature Precision Au-Based Die-Attach Preforms at International Microwave Symposium

<u>Indium Corporation</u>[®] will feature its high-reliability, Au-based precision die-attach (PDA) preforms for critical laser and RF applications at the <u>International Microwave Symposium</u>, Denver, Colo., June 19–24.

Indium Corporation is the leading solder supplier for laser, optical, and RF microwave applications. Au-based alloys are a great choice to ensure the best performance and reliability possible for applications requiring a highmelting die-attach solder. In addition to meeting the demanding thermal and electrical requirements for highreliability applications, they also provide the strongest corrosion- and oxidation-resistant solder joint possible.



Semiconductor laser and RF power die-attach applications require the highest quality, ultraprecise solder preforms to ensure accuracy and repeatability during assembly for a guaranteed highly-reliable end product. Indium Corporation's Au-based PDA preforms offer the highest level of quality available to deliver the best performance possible in critical, high-reliability die-attach applications. Features include:

- Highly accurate thickness control
- Precision edge quality, virtually burr-free
- Optimized cleanliness control
- Default waffle-pack method

Indium Corporation's AuLTRATM 75 is an off-eutectic AuSn preform solution (75Au25Sn) designed to improve intermetallic reliability in applications using a die with a thicker gold plating, such as a GaN die used for high-frequency, high-power RF power amplifier devices for 5G and other critical military and aerospace wireless communications. AuLTRATM 75 helps improve the operation of these critical technologies by offering a lower gold content, allowing for the absorption of gold from the die, and thereby ensuring a strong solder bond.

AuSn preform solutions:

- Deliver improved wetting and voiding
- Allow for adjustment of the final solder joint composition
- Are available in 78Au22Sn and 79Au21Sn formulations

Indium Corporation's <u>AuLTRA™ ThInFORMS™</u> are 0.00035" thick (0.00889mm or 8.89µm) 80Au20Sn preforms that improve the overall operational efficiency of high-output lasers. AuLTRA[™] ThInFORMS[™] help combat common issues such as:

- Shorting—reduced solder volume inhibits wicking up the die, minimizing the risk of shorting
- Poor thermal transfer—the ultra-thin 0.00035" preform reduces bondline thickness, thus improving thermal transfer and increasing the longevity and performance of the device.

To learn more about Indium Corporation's precision Au-based preforms, visit <u>www.indium.com/products/solders/gold/gold-preforms</u> or stop by booth #9012 at the show.

About Indium Corporation

Indium Corporation[®] is a premier materials refiner, smelter, manufacturer, and supplier to the global electronics, semiconductor, thin-film, and thermal management markets. Products include solders and fluxes; brazes; thermal interface materials; sputtering targets; indium, gallium, germanium, and tin metals and inorganic compounds; and NanoFoil[®]. Founded in 1934, the company has global technical support and factories located in China, Germany, India, Malaysia, Singapore, South Korea, the United Kingdom, and the U.S.

For more information about Indium Corporation, visit <u>www.indium.com</u> or email <u>jhuang@indium.com</u>. You can also follow our experts, From One Engineer To Another[®] (#FOETA), at <u>www.linkedin.com/company/indium-corporation/</u> or <u>@IndiumCorp</u>.

About International Microwave Symposium

For 70 years, IMS has brought together a unique mix of international RF and microwave experts presenting the latest research and showcasing the newest products and services. IMS includes education and networking opportunities as well as an exhibition. Learn more at <u>ims-ieee.org</u>.

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